

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC109N10NS3 G	**Issued**	24. August 2021
MA#	MA001584332		
Package	PG-TDSON-8-1	**Weight***	120.92 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.461	2.04	2.04	20352	20352
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	iron	7439-89-6	0.038	0.03		313	
	non noble metal	copper	7440-50-8	37.762	31.21	31.25	312295	312702
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	471	471
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		690	
	plastics	epoxy resin	-	5.926	4.90		49006	
	inorganic material	silicondioxide	60676-86-0	35.721	29.54	34.51	295418	345114
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	12005	12005
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1369	1369
solder	non noble metal	tin	7440-31-5	0.046	0.04		380	
	noble metal	silver	7440-22-4	0.057	0.05		475	
	non noble metal	lead	7439-92-1	2.192	1.81	1.90	18131	18986
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		185	
	noble metal	silver	7440-22-4	1.289	1.07		10664	
	non noble metal	copper	7440-50-8	22.292	18.44	19.54	184356	195260
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		94	
	non noble metal	copper	7440-50-8	11.320	9.36	9.37	93619	93741
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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